

# 74AHC04-Q100; 74AHCT04-Q100

Hex inverter

Rev. 1 — 2 April 2013

Product data sheet

## 1. General description

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The 74AHC04-Q100; 74AHCT04-Q100 is a high-speed Si-gate CMOS device and is pin compatible with Low-power Schottky TTL (LSTTL). It is specified in compliance with JEDEC standard No. 7-A.

The 74AHC04-Q100; 74AHCT04-Q100 provides six inverting buffers.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

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- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Balanced propagation delays
- Inputs accept voltages higher than  $V_{CC}$
- Input levels:
  - ◆ For 74AHC04-Q100: CMOS level
  - ◆ For 74AHCT04-Q100: TTL level
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )
- Multiple package options

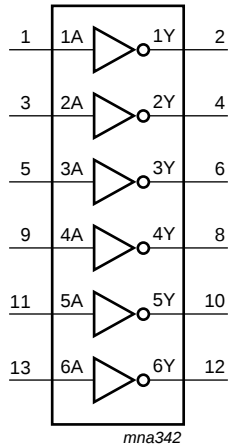


3. Ordering information

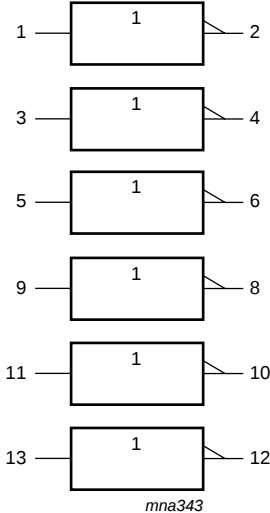
Table 1. Ordering information

| Type number          | Package           |          |                                                                                                                              |          |
|----------------------|-------------------|----------|------------------------------------------------------------------------------------------------------------------------------|----------|
|                      | Temperature range | Name     | Description                                                                                                                  | Version  |
| <b>74AHC04-Q100</b>  |                   |          |                                                                                                                              |          |
| 74AHC04D-Q100        | −40 °C to +125 °C | SO14     | plastic small outline package; 14 leads; body width 3.9 mm                                                                   | SOT108-1 |
| 74AHC04PW-Q100       | −40 °C to +125 °C | TSSOP14  | plastic thin shrink small outline package; 14 leads; body width 4.4 mm                                                       | SOT402-1 |
| 74AHC04BQ-Q100       | −40 °C to +125 °C | DHVQFN14 | plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm | SOT762-1 |
| <b>74AHCT04-Q100</b> |                   |          |                                                                                                                              |          |
| 74AHCT04D-Q100       | −40 °C to +125 °C | SO14     | plastic small outline package; 14 leads; body width 3.9 mm                                                                   | SOT108-1 |
| 74AHCT04PW-Q100      | −40 °C to +125 °C | TSSOP14  | plastic thin shrink small outline package; 14 leads; body width 4.4 mm                                                       | SOT402-1 |
| 74AHCT04BQ-Q100      | −40 °C to +125 °C | DHVQFN14 | plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 × 3 × 0.85 mm | SOT762-1 |

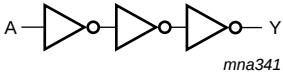
4. Functional diagram



**Fig 1. Logic symbol**



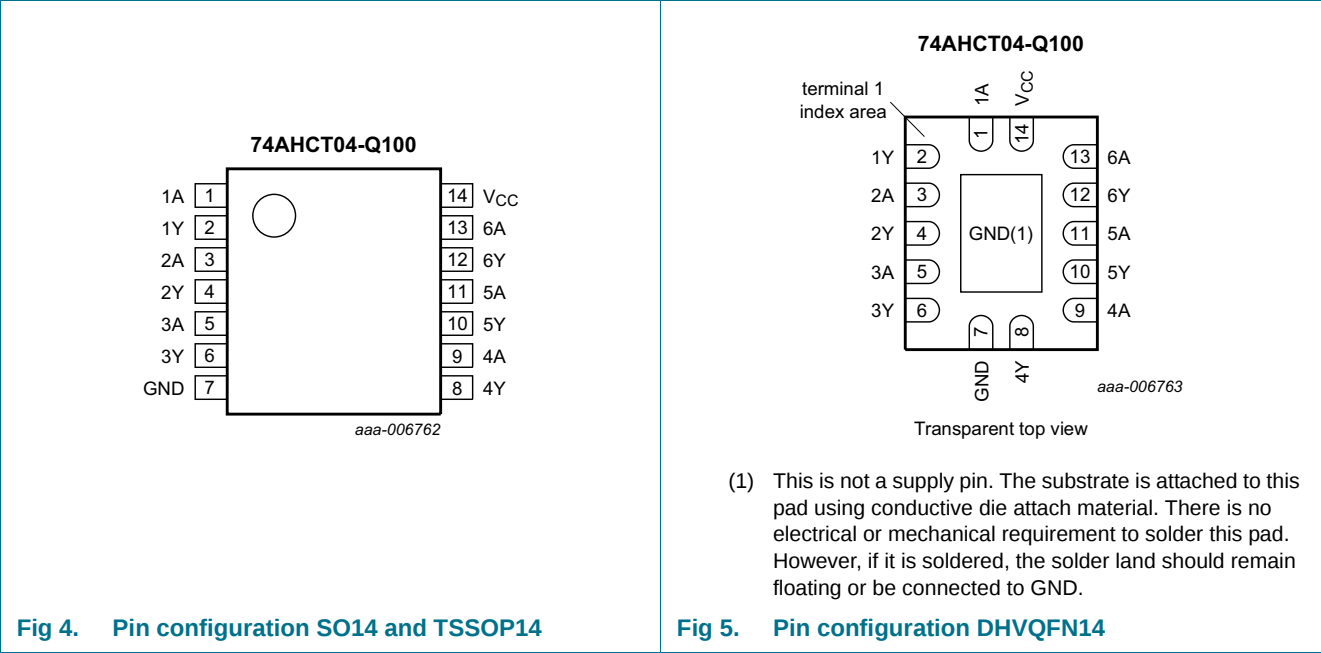
**Fig 2. IEC logic symbol**



**Fig 3. Logic diagram (one inverter)**

5. Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

| Symbol                 | Pin                | Description    |
|------------------------|--------------------|----------------|
| 1A, 2A, 3A, 4A, 5A, 6A | 1, 3, 5, 9, 11, 13 | data input     |
| 1Y, 2Y, 3Y, 4Y, 5Y, 6Y | 2, 4, 6, 8, 10, 12 | data output    |
| GND                    | 7                  | ground (0 V)   |
| V <sub>CC</sub>        | 14                 | supply voltage |

6. Functional description

Table 3. Function table<sup>[1]</sup>

| Input nA | Output nY |
|----------|-----------|
| L        | H         |
| H        | L         |

[1] H = HIGH voltage level;  
L = LOW voltage level.

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol    | Parameter               | Conditions                               | Min                | Max  | Unit |
|-----------|-------------------------|------------------------------------------|--------------------|------|------|
| $V_{CC}$  | supply voltage          |                                          | -0.5               | +7.0 | V    |
| $V_I$     | input voltage           |                                          | -0.5               | +7.0 | V    |
| $I_{IK}$  | input clamping current  | $V_I < -0.5$ V                           | <sup>[1]</sup> -20 | -    | mA   |
| $I_{OK}$  | output clamping current | $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V | <sup>[1]</sup> -20 | +20  | mA   |
| $I_O$     | output current          | $V_O = -0.5$ V to $(V_{CC} + 0.5)$ V     | -25                | +25  | mA   |
| $I_{CC}$  | supply current          |                                          | -                  | +75  | mA   |
| $I_{GND}$ | ground current          |                                          | -75                | -    | mA   |
| $T_{stg}$ | storage temperature     |                                          | -65                | +150 | °C   |
| $P_{tot}$ | total power dissipation | $T_{amb} = -40$ °C to +125 °C            | <sup>[2]</sup> -   | 500  | mW   |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For SO14 packages: above 70 °C the value of  $P_{tot}$  derates linearly at 8 mW/K.

For TSSOP14 packages: above 60 °C the value of  $P_{tot}$  derates linearly at 5.5 mW/K.

For DHVQFN14 packages: above 60 °C the value of  $P_{tot}$  derates linearly at 4.5 mW/K.

## 8. Recommended operating conditions

**Table 5. Operating conditions**

| Symbol               | Parameter                           | Conditions                | Min | Typ | Max      | Unit |
|----------------------|-------------------------------------|---------------------------|-----|-----|----------|------|
| <b>74AHC04-Q100</b>  |                                     |                           |     |     |          |      |
| $V_{CC}$             | supply voltage                      |                           | 2.0 | 5.0 | 5.5      | V    |
| $V_I$                | input voltage                       |                           | 0   | -   | 5.5      | V    |
| $V_O$                | output voltage                      |                           | 0   | -   | $V_{CC}$ | V    |
| $T_{amb}$            | ambient temperature                 |                           | -40 | +25 | +125     | °C   |
| $\Delta t/\Delta V$  | input transition rise and fall rate | $V_{CC} = 3.0$ V to 3.6 V | -   | -   | 100      | ns/V |
|                      |                                     | $V_{CC} = 4.5$ V to 5.5 V | -   | -   | 20       | ns/V |
| <b>74AHCT04-Q100</b> |                                     |                           |     |     |          |      |
| $V_{CC}$             | supply voltage                      |                           | 4.5 | 5.0 | 5.5      | V    |
| $V_I$                | input voltage                       |                           | 0   | -   | 5.5      | V    |
| $V_O$                | output voltage                      |                           | 0   | -   | $V_{CC}$ | V    |
| $T_{amb}$            | ambient temperature                 |                           | -40 | +25 | +125     | °C   |
| $\Delta t/\Delta V$  | input transition rise and fall rate | $V_{CC} = 4.5$ V to 5.5 V | -   | -   | 20       | ns/V |

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol          | Parameter                 | Conditions                                                                             | 25 °C |     |      | –40 °C to +85 °C |      | –40 °C to +125 °C |      | Unit |
|-----------------|---------------------------|----------------------------------------------------------------------------------------|-------|-----|------|------------------|------|-------------------|------|------|
|                 |                           |                                                                                        | Min   | Typ | Max  | Min              | Max  | Min               | Max  |      |
| 74AHC04-Q100    |                           |                                                                                        |       |     |      |                  |      |                   |      |      |
| V <sub>IH</sub> | HIGH-level input voltage  | V <sub>CC</sub> = 2.0 V                                                                | 1.5   | -   | -    | 1.5              | -    | 1.5               | -    | V    |
|                 |                           | V <sub>CC</sub> = 3.0 V                                                                | 2.1   | -   | -    | 2.1              | -    | 2.1               | -    | V    |
|                 |                           | V <sub>CC</sub> = 5.5 V                                                                | 3.85  | -   | -    | 3.85             | -    | 3.85              | -    | V    |
| V <sub>IL</sub> | LOW-level input voltage   | V <sub>CC</sub> = 2.0 V                                                                | -     | -   | 0.5  | -                | 0.5  | -                 | 0.5  | V    |
|                 |                           | V <sub>CC</sub> = 3.0 V                                                                | -     | -   | 0.9  | -                | 0.9  | -                 | 0.9  | V    |
|                 |                           | V <sub>CC</sub> = 5.5 V                                                                | -     | -   | 1.65 | -                | 1.65 | -                 | 1.65 | V    |
| V <sub>OH</sub> | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>                                    |       |     |      |                  |      |                   |      |      |
|                 |                           | I <sub>O</sub> = –50 μA; V <sub>CC</sub> = 2.0 V                                       | 1.9   | 2.0 | -    | 1.9              | -    | 1.9               | -    | V    |
|                 |                           | I <sub>O</sub> = –50 μA; V <sub>CC</sub> = 3.0 V                                       | 2.9   | 3.0 | -    | 2.9              | -    | 2.9               | -    | V    |
|                 |                           | I <sub>O</sub> = –50 μA; V <sub>CC</sub> = 4.5 V                                       | 4.4   | 4.5 | -    | 4.4              | -    | 4.4               | -    | V    |
|                 |                           | I <sub>O</sub> = –4.0 mA; V <sub>CC</sub> = 3.0 V                                      | 2.58  | -   | -    | 2.48             | -    | 2.40              | -    | V    |
| V <sub>OL</sub> | LOW-level output voltage  | I <sub>O</sub> = –8.0 mA; V <sub>CC</sub> = 4.5 V                                      | 3.94  | -   | -    | 3.80             | -    | 3.70              | -    | V    |
|                 |                           | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>                                    |       |     |      |                  |      |                   |      |      |
|                 |                           | I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 2.0 V                                        | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                 |                           | I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 3.0 V                                        | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                 |                           | I <sub>O</sub> = 50 μA; V <sub>CC</sub> = 4.5 V                                        | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
| I <sub>I</sub>  | input leakage current     | I <sub>O</sub> = 4.0 mA; V <sub>CC</sub> = 3.0 V                                       | -     | -   | 0.36 | -                | 0.44 | -                 | 0.55 | V    |
|                 |                           | I <sub>O</sub> = 8.0 mA; V <sub>CC</sub> = 4.5 V                                       | -     | -   | 0.36 | -                | 0.44 | -                 | 0.55 | V    |
|                 |                           | V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V                          | -     | -   | 0.1  | -                | 1.0  | -                 | 2.0  | μA   |
|                 |                           | V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V | -     | -   | 2.0  | -                | 20   | -                 | 40   | μA   |
|                 |                           | V <sub>I</sub> = V <sub>CC</sub> or GND                                                | -     | 3   | 10   | -                | 10   | -                 | 10   | pF   |
| 74AHCT04-Q100   |                           |                                                                                        |       |     |      |                  |      |                   |      |      |
| V <sub>IH</sub> | HIGH-level input voltage  | V <sub>CC</sub> = 4.5 V to 5.5 V                                                       | 2.0   | -   | -    | 2.0              | -    | 2.0               | -    | V    |
| V <sub>IL</sub> | LOW-level input voltage   | V <sub>CC</sub> = 4.5 V to 5.5 V                                                       | -     | -   | 0.8  | -                | 0.8  | -                 | 0.8  | V    |
| V <sub>OH</sub> | HIGH-level output voltage | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V          |       |     |      |                  |      |                   |      |      |
|                 |                           | I <sub>O</sub> = –50 μA                                                                | 4.4   | 4.5 | -    | 4.4              | -    | 4.4               | -    | V    |
|                 |                           | I <sub>O</sub> = –8.0 mA                                                               | 3.94  | -   | -    | 3.80             | -    | 3.70              | -    | V    |
| V <sub>OL</sub> | LOW-level output voltage  | V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V          |       |     |      |                  |      |                   |      |      |
|                 |                           | I <sub>O</sub> = 50 μA                                                                 | -     | 0   | 0.1  | -                | 0.1  | -                 | 0.1  | V    |
|                 |                           | I <sub>O</sub> = 8.0 mA                                                                | -     | -   | 0.36 | -                | 0.44 | -                 | 0.55 | V    |
| I <sub>I</sub>  | input leakage current     | V <sub>I</sub> = 5.5 V or GND; V <sub>CC</sub> = 0 V to 5.5 V                          | -     | -   | 0.1  | -                | 1.0  | -                 | 2.0  | μA   |

**Table 6.** Static characteristics ...continued

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

| Symbol          | Parameter                 | Conditions                                                                                                         | 25 °C |     |      | –40 °C to +85 °C |     | –40 °C to +125 °C |     | Unit    |
|-----------------|---------------------------|--------------------------------------------------------------------------------------------------------------------|-------|-----|------|------------------|-----|-------------------|-----|---------|
|                 |                           |                                                                                                                    | Min   | Typ | Max  | Min              | Max | Min               | Max |         |
| $I_{CC}$        | supply current            | $V_I = V_{CC}$ or GND; $I_O = 0$ A;<br>$V_{CC} = 5.5$ V                                                            | -     | -   | 2.0  | -                | 20  | -                 | 40  | $\mu$ A |
| $\Delta I_{CC}$ | additional supply current | per input pin;<br>$V_I = V_{CC} - 2.1$ V; other pins at $V_{CC}$ or GND; $I_O = 0$ A;<br>$V_{CC} = 4.5$ V to 5.5 V | -     | -   | 1.35 | -                | 1.5 | -                 | 1.5 | mA      |
| $C_i$           | input capacitance         | $V_I = V_{CC}$ or GND                                                                                              | -     | 3   | 10   | -                | 10  | -                 | 10  | pF      |

## 10. Dynamic characteristics

**Table 7.** Dynamic characteristicsVoltages are referenced to GND (ground = 0 V); for test circuit see [Figure 7](#).

| Symbol | Parameter | Conditions | 25 °C |                    |     | –40 °C to +85 °C |     | –40 °C to +125 °C |     | Unit |
|--------|-----------|------------|-------|--------------------|-----|------------------|-----|-------------------|-----|------|
|        |           |            | Min   | Typ <sup>[1]</sup> | Max | Min              | Max | Min               | Max |      |

### 74AHC04-Q100

|          |                               |                                                       |   |      |      |     |      |     |      |    |
|----------|-------------------------------|-------------------------------------------------------|---|------|------|-----|------|-----|------|----|
| $t_{pd}$ | propagation delay             | nA to nY; see <a href="#">Figure 6</a> <sup>[2]</sup> |   |      |      |     |      |     |      |    |
|          |                               | $V_{CC} = 3.0$ V to 3.6 V                             |   |      |      |     |      |     |      |    |
|          |                               | $C_L = 15$ pF                                         | - | 4.0  | 8.5  | 1.0 | 10.5 | 1.0 | 11.0 | ns |
|          |                               | $C_L = 50$ pF                                         | - | 6.0  | 11.4 | 1.0 | 13   | 1.0 | 14.5 | ns |
|          |                               | $V_{CC} = 4.5$ V to 5.5 V                             |   |      |      |     |      |     |      |    |
|          |                               | $C_L = 15$ pF                                         | - | 3.0  | 5.5  | 1.0 | 6.5  | 1.0 | 7.0  | ns |
| $C_{PD}$ | power dissipation capacitance | $f_i = 1$ MHz; $V_I =$ GND to $V_{CC}$ <sup>[3]</sup> | - | 13.5 | -    | -   | -    | -   | -    | pF |
|          |                               |                                                       |   |      |      |     |      |     |      |    |

### 74AHCT04-Q100; $V_{CC} = 4.5$ V to 5.5 V

|          |                               |                                                       |   |      |     |     |     |     |      |    |
|----------|-------------------------------|-------------------------------------------------------|---|------|-----|-----|-----|-----|------|----|
| $t_{pd}$ | propagation delay             | nA to nY; see <a href="#">Figure 6</a> <sup>[2]</sup> |   |      |     |     |     |     |      |    |
|          |                               | $C_L = 15$ pF                                         | - | 3.0  | 6.7 | 1.0 | 7.5 | 1.0 | 8.5  | ns |
|          |                               | $C_L = 50$ pF                                         | - | 4.5  | 7.7 | 1.0 | 8.5 | 1.0 | 10.0 | ns |
| $C_{PD}$ | power dissipation capacitance | $f_i = 1$ MHz; $V_I =$ GND to $V_{CC}$ <sup>[3]</sup> | - | 13.9 | -   | -   | -   | -   | -    | pF |

[1] Typical values are measured at nominal supply voltage ( $V_{CC} = 3.3$  V and  $V_{CC} = 5.0$  V).[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu$ W). $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$  where: $f_i$  = input frequency in MHz; $f_o$  = output frequency in MHz; $C_L$  = output load capacitance in pF; $V_{CC}$  = supply voltage in V; $N$  = number of inputs switching; $\Sigma(C_L \times V_{CC}^2 \times f_o)$  = sum of the outputs.

11. Waveforms

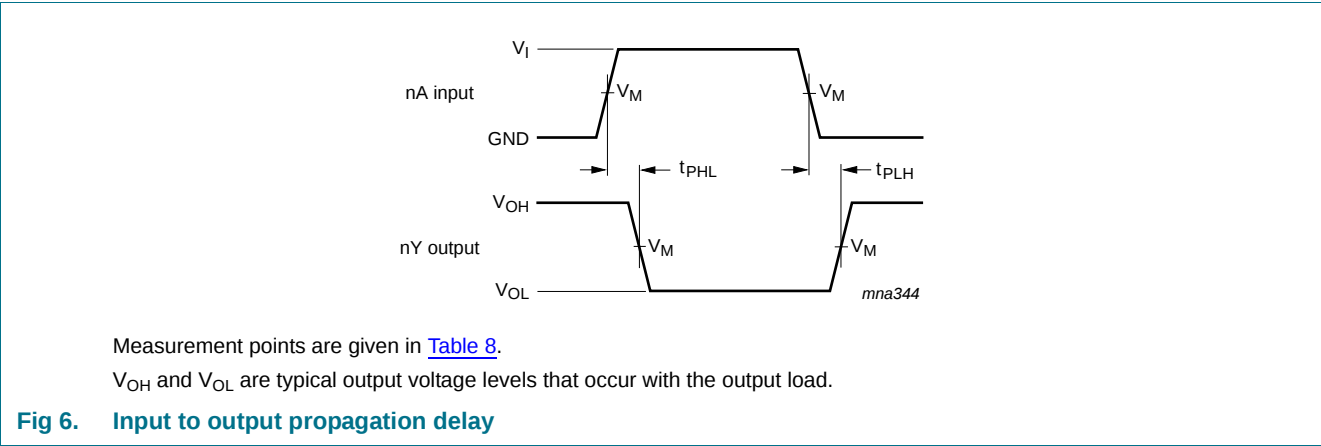


Table 8. Measurement points

| Type          | Input               | Output              |
|---------------|---------------------|---------------------|
|               | $V_M$               | $V_M$               |
| 74AHC04-Q100  | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ |
| 74AHCT04-Q100 | 1.5 V               | $0.5 \times V_{CC}$ |

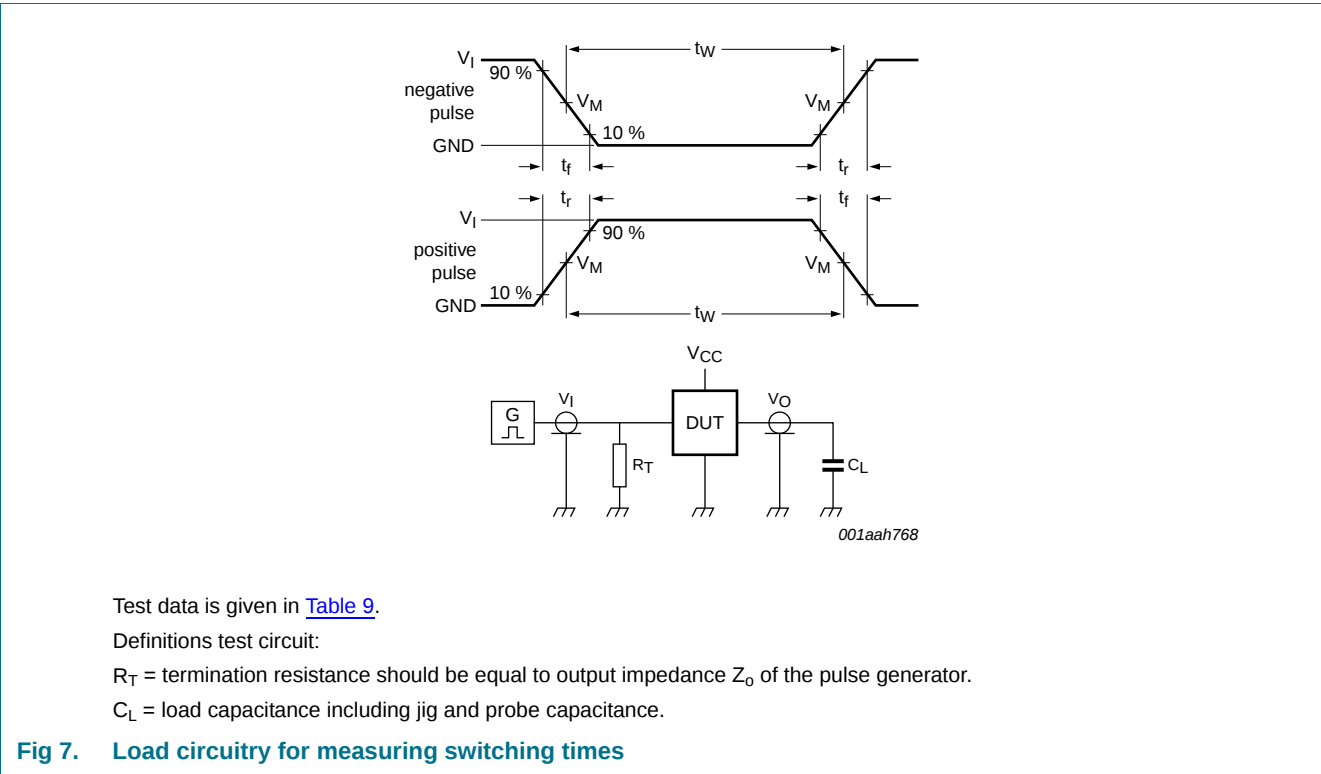


Table 9. Test data

| Type          | Input           |                                 | Load           | Test                                |
|---------------|-----------------|---------------------------------|----------------|-------------------------------------|
|               | V <sub>I</sub>  | t <sub>r</sub> , t <sub>f</sub> | C <sub>L</sub> |                                     |
| 74AHC04-Q100  | V <sub>CC</sub> | ≤ 3.0 ns                        | 15 pF, 50 pF   | t <sub>PLH</sub> , t <sub>PHL</sub> |
| 74AHCT04-Q100 | 3.0 V           | ≤ 3.0 ns                        | 15 pF, 50 pF   | t <sub>PLH</sub> , t <sub>PHL</sub> |

12. Package outline

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

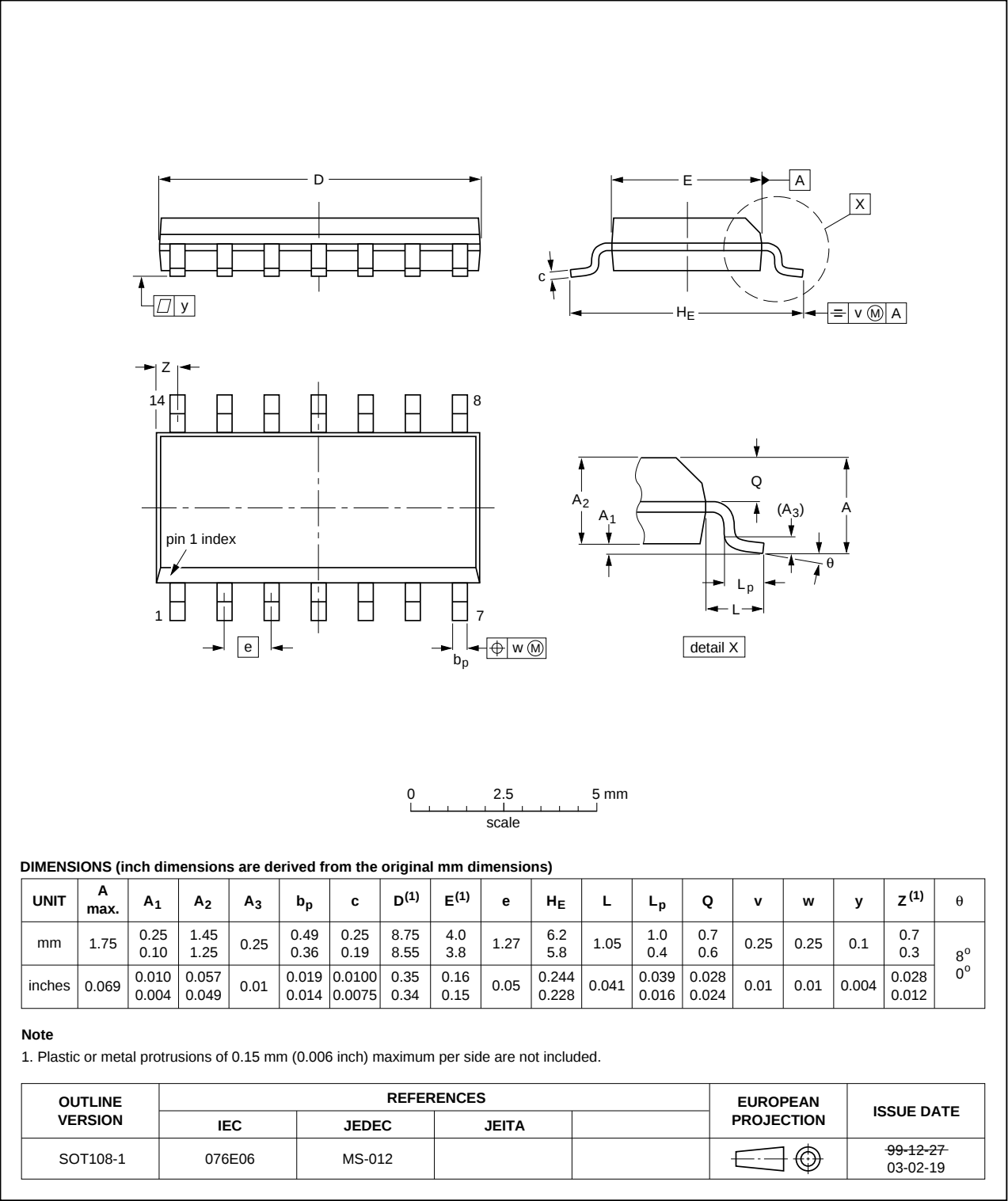


Fig 8. Package outline SOT108-1 (SO14)

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm

SOT402-1

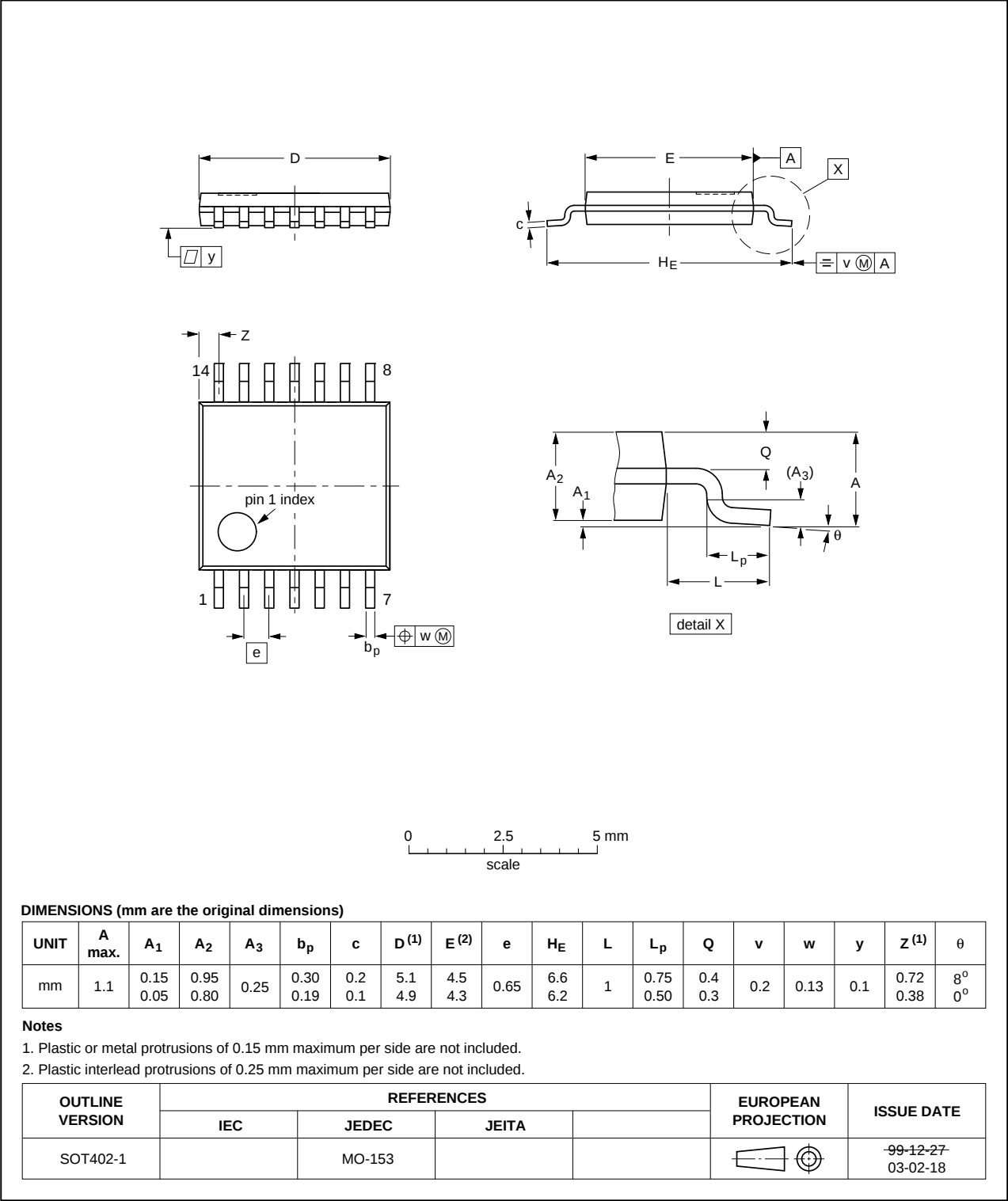


Fig 9. Package outline SOT402-1 (TSSOP14)

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm

SOT762-1

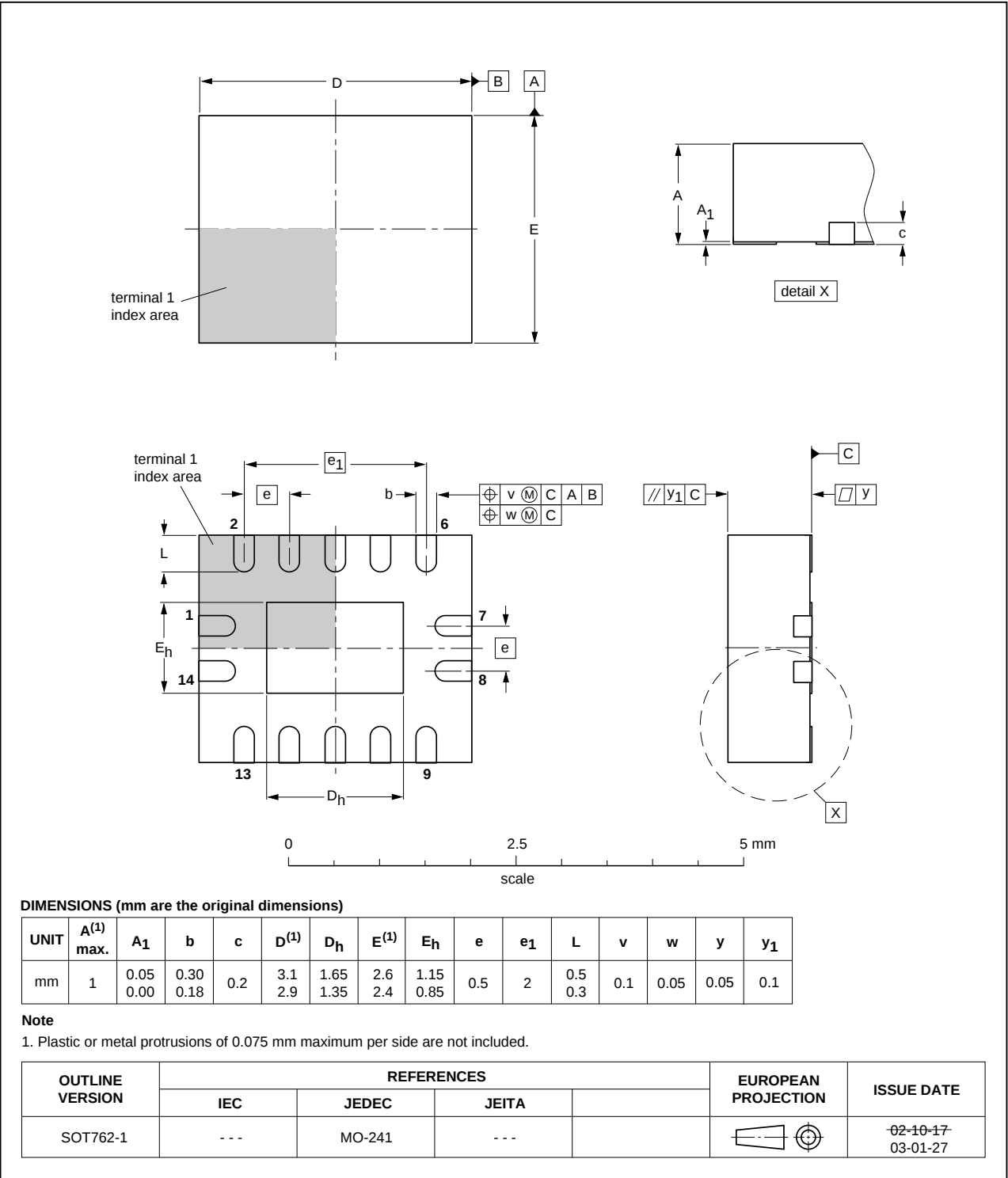


Fig 10. Package outline SOT762-1 (DHVQFN14)

## 13. Abbreviations

Table 10. Abbreviations

| Acronym | Description                                    |
|---------|------------------------------------------------|
| CDM     | Charged Device Model                           |
| CMOS    | Complementary Metal-Oxide Semiconductor        |
| DUT     | Device Under Test                              |
| ESD     | ElectroStatic Discharge                        |
| HBM     | Human Body Model                               |
| LSTTL   | Low-power Schottky Transistor-Transistor Logic |
| MIL     | Military                                       |
| MM      | Machine Model                                  |

## 14. Revision history

Table 11. Revision history

| Document ID           | Release date | Data sheet status  | Change notice | Supersedes |
|-----------------------|--------------|--------------------|---------------|------------|
| 74AHC_AHCT04_Q100 v.1 | 20130402     | Product data sheet | -             | -          |

## 15. Legal information

### 15.1 Data sheet status

| Document status <sup>[1][2]</sup> | Product status <sup>[3]</sup> | Definition                                                                            |
|-----------------------------------|-------------------------------|---------------------------------------------------------------------------------------|
| Objective [short] data sheet      | Development                   | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet    | Qualification                 | This document contains data from the preliminary specification.                       |
| Product [short] data sheet        | Production                    | This document contains the product specification.                                     |

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

### 15.2 Definitions

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